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United States Patent [19]

Honma

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[45] **Date of Patent: **Jan. 12, 1999**

[54] **WAFER BOAT FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[73] Assignee: **Tokyo Electron Ltd.**, Tokyo-To, Japan

[**] Term: **14 Years**

[21] Appl. No.: **74,281**

[22] Filed: **Jul. 24, 1997**

[30] **Foreign Application Priority Data**

Jan. 31, 1997 [JP] Japan 9-2659

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144, D15/144.1, 199; 414/935–941, 217, 147; 437/247, 946; D6/407, 629

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[57] **CLAIM**

The ornamental design for wafer boat for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. **1** a perspective view of a wafer boat for use in a semiconductor wafer heat processing apparatus;
FIG. **2** a front elevational view thereof;
FIG. **3** a top plan view thereof;
FIG. **4** a bottom plan view thereof;
FIG. **5** a cross sectional view taken along line V-V in FIG. **2**;
FIG. **6** a right side view thereof, the left side view being a mirror image of the right view;
FIG. **7** a rear elevational view thereof; and,
FIG. **8** a cross sectional view taken along line VIII-VIII in FIG. **2**.

1 Claim, 4 Drawing Sheets

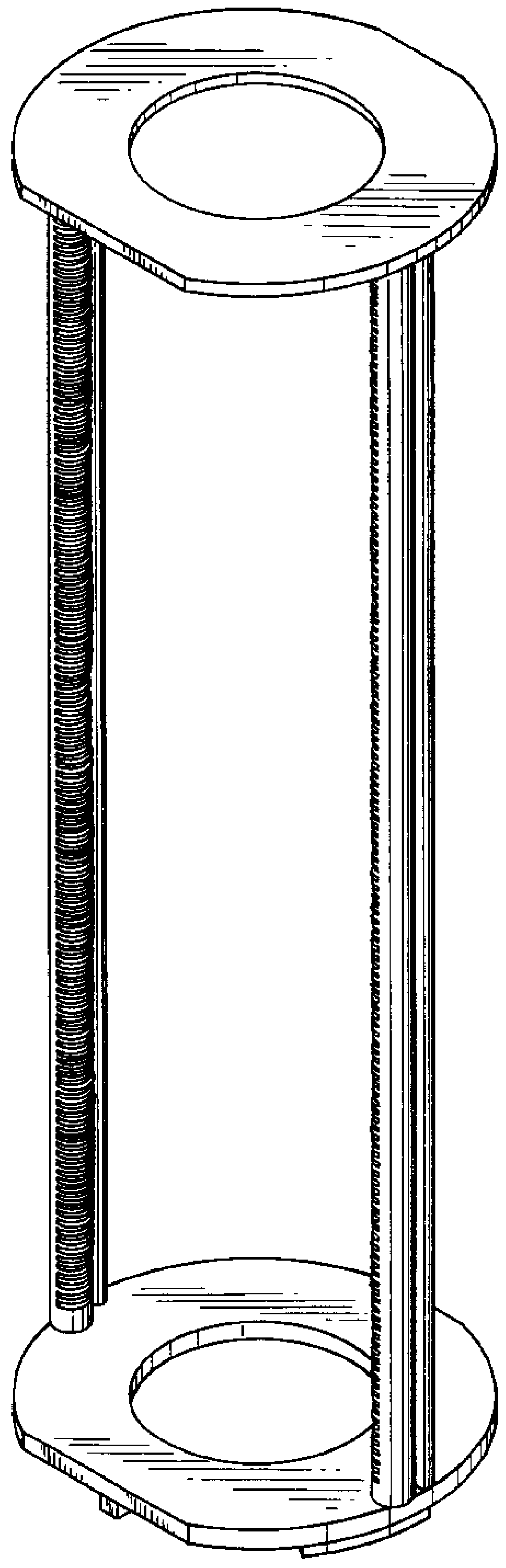

FIG. 1

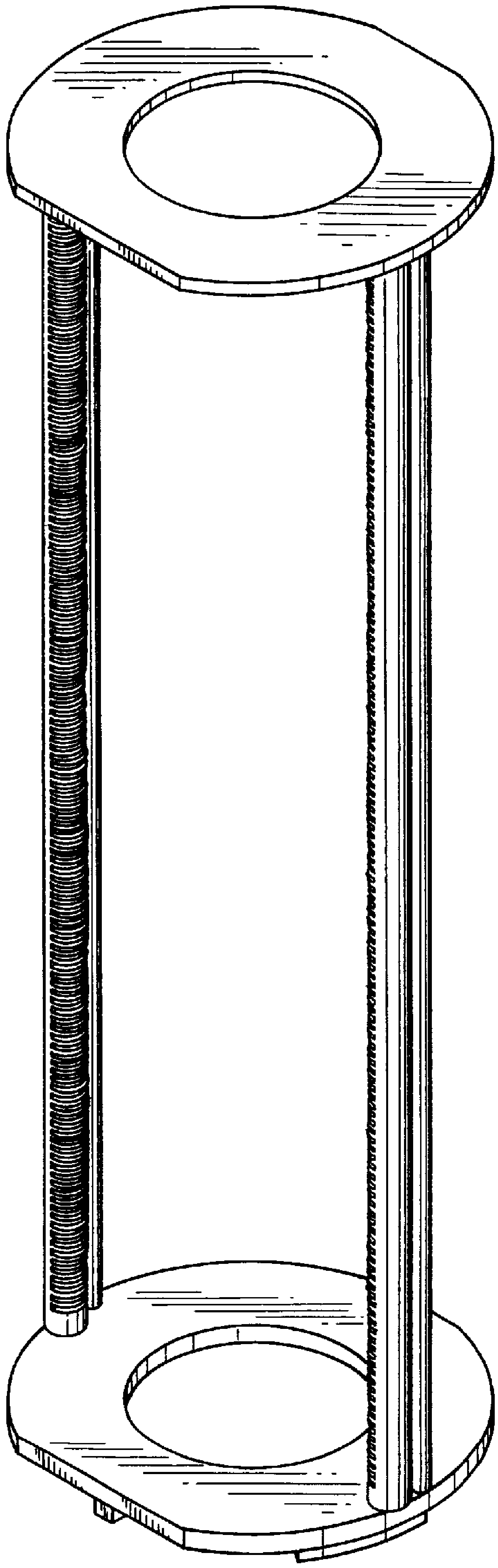

FIG. 2

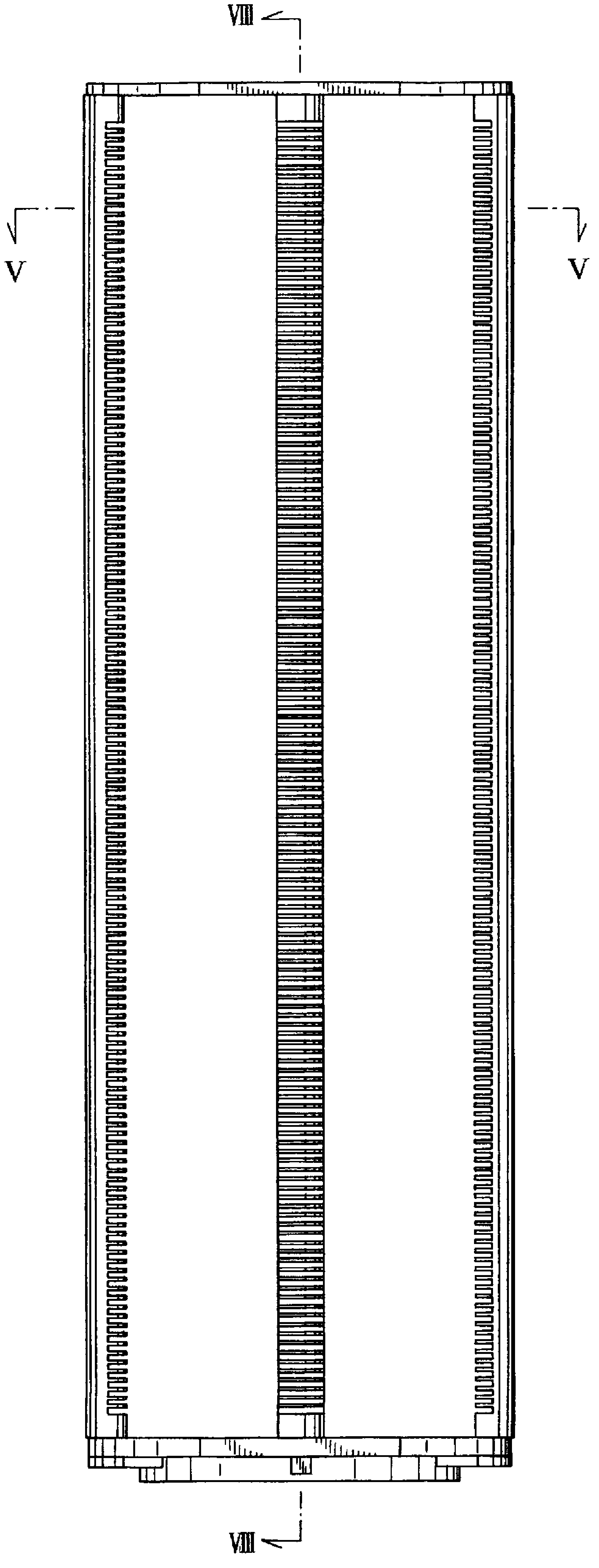

FIG. 3

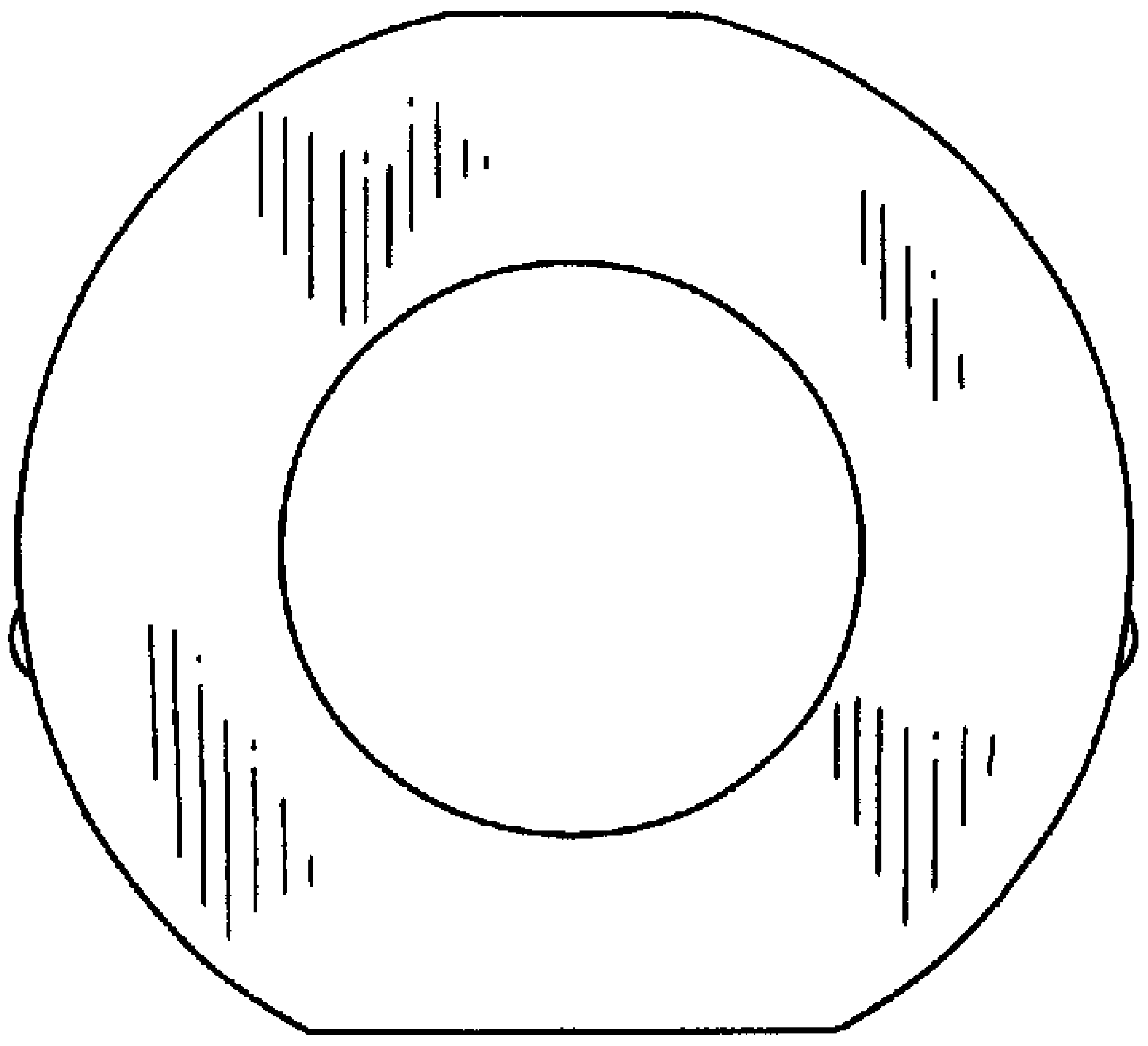

FIG. 4

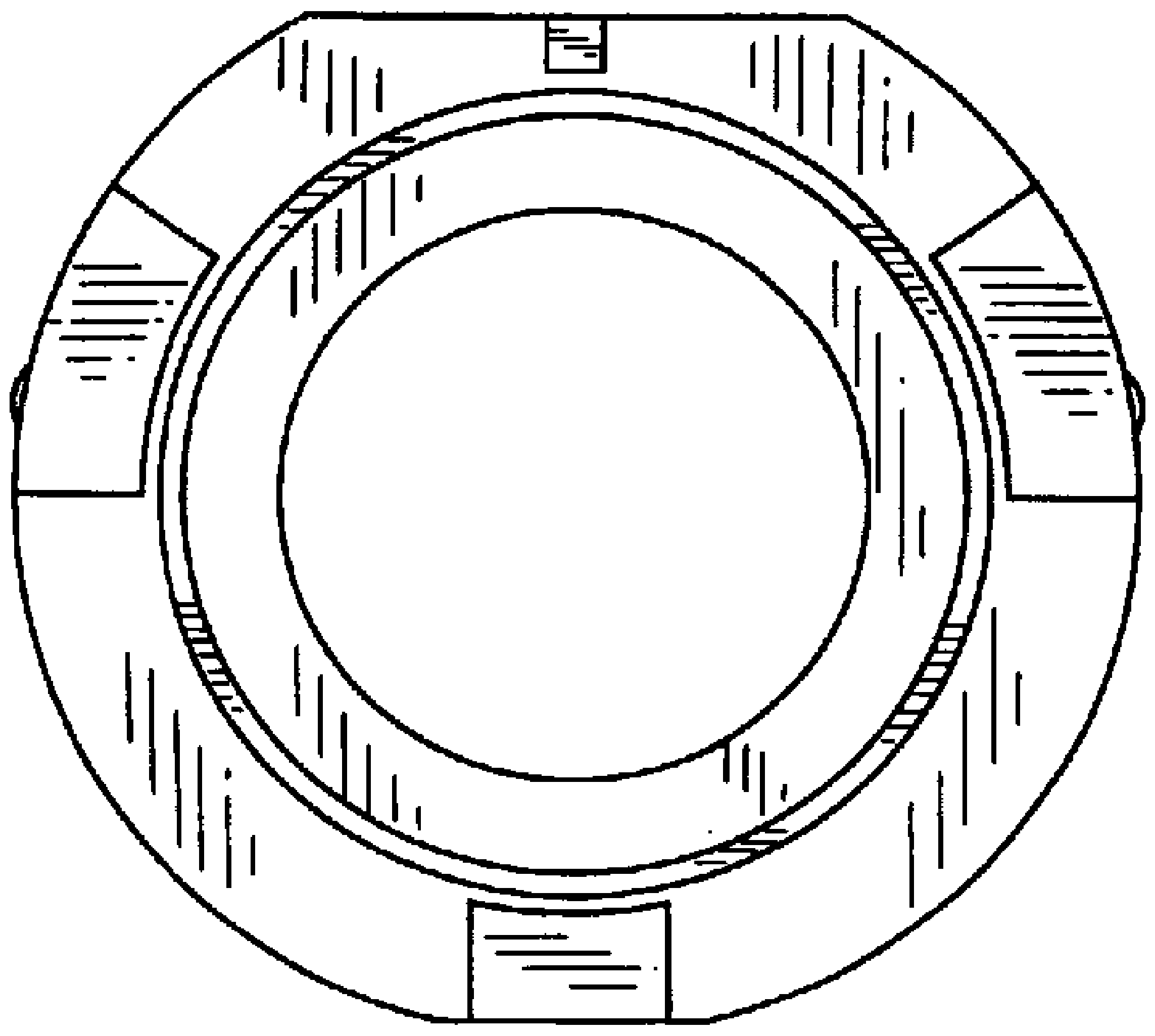

FIG. 5

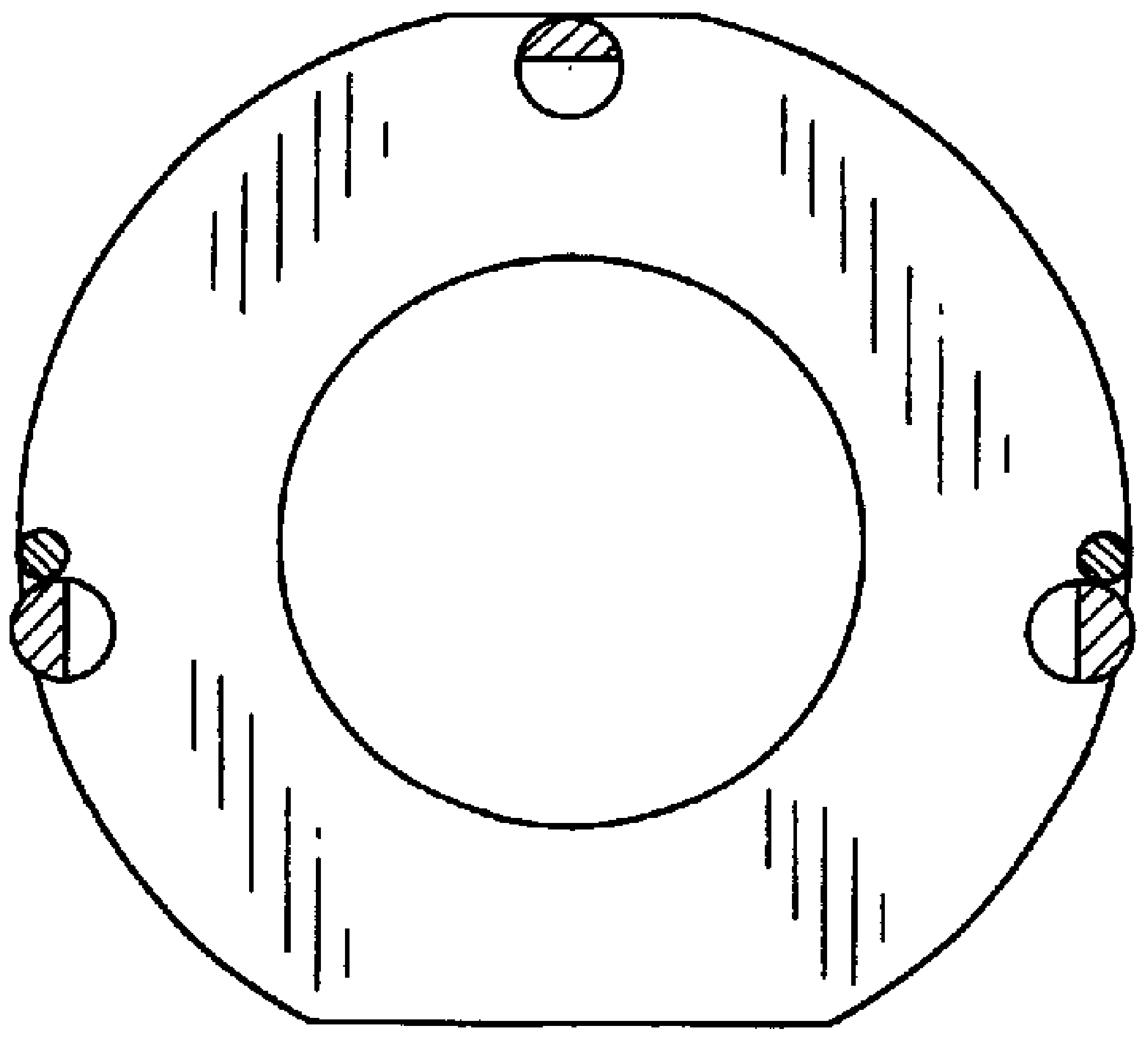

FIG. 6

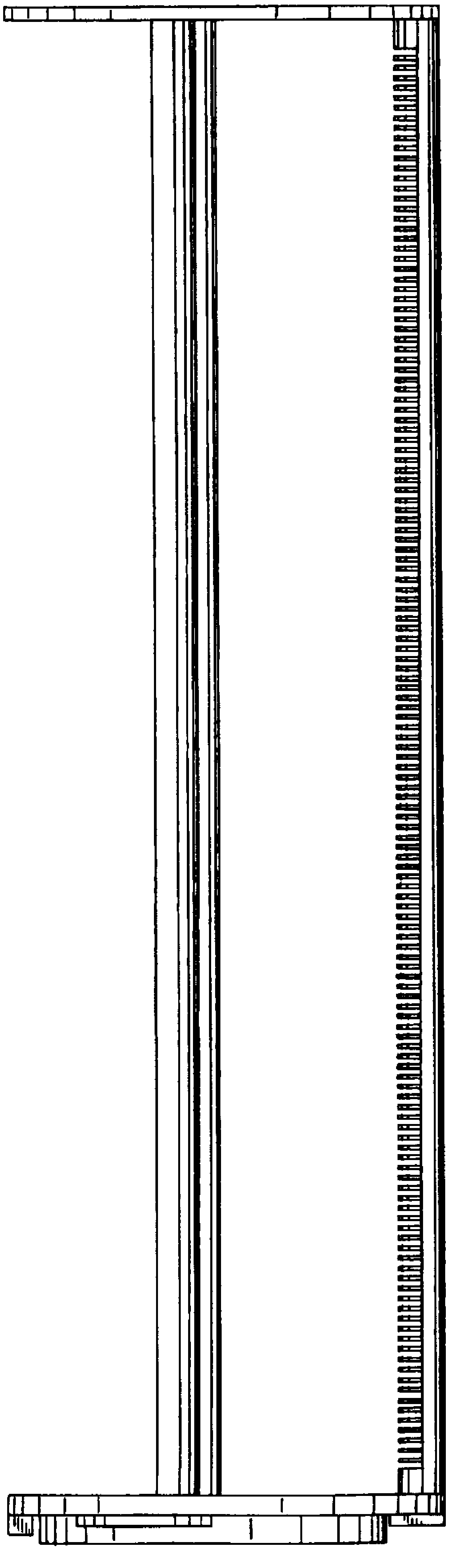

FIG. 7

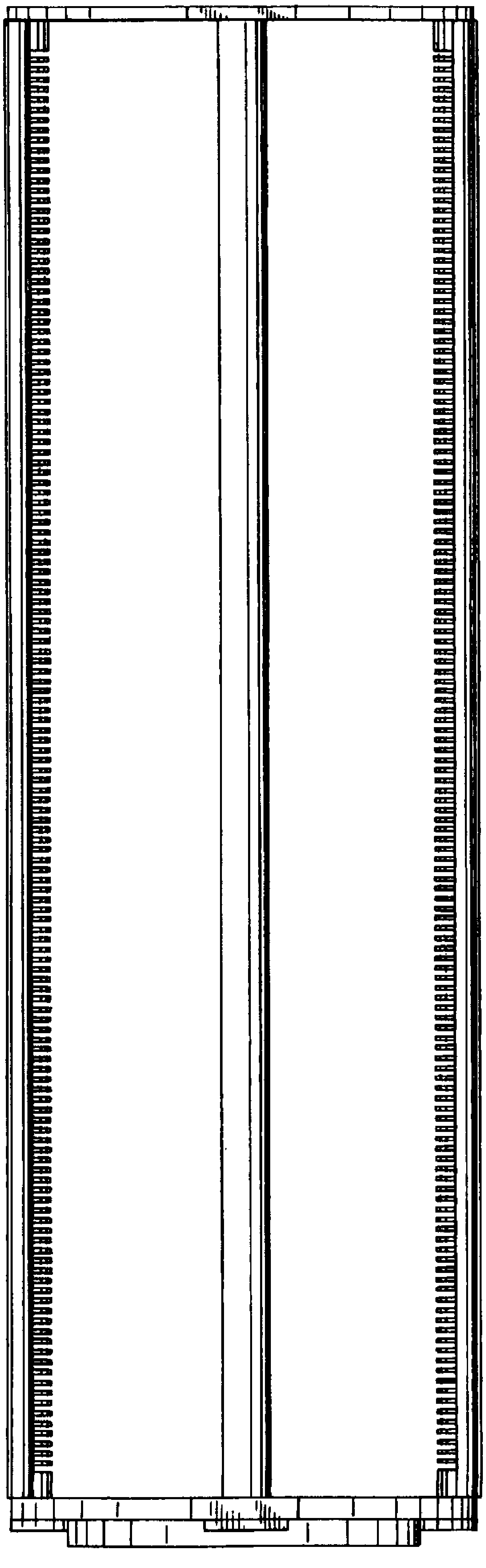

FIG. 8